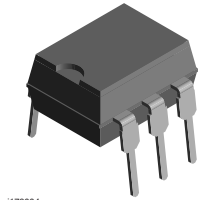
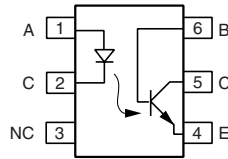


## Optocoupler, Phototransistor Output, with Base Connection



1179004



### DESCRIPTION

This data sheet presents five families of Vishay Industry Standard Single Channel Phototransistor Couplers. These families include the 4N35/4N36/4N37/ 4N38 couplers.

Each optocoupler consists of gallium arsenide infrared LED and a silicon NPN phototransistor.

These couplers are Underwriters Laboratories (UL) listed to comply with a 5300 V<sub>RMS</sub> isolation test voltage.

This isolation performance is accomplished through Vishay double molding isolation manufacturing process. Compliance to DIN EN 60747-5-5 partial discharge isolation specification is available for these families by ordering option 1.

These isolation processes and the Vishay ISO9001 quality program results in the highest isolation performance available for a commercial plastic phototransistor optocoupler.

The devices are available in lead formed configuration suitable for surface mounting and are available either on tape and reel, or in standard tube shipping containers.

Note:

For additional design information see application note 45 normalized curves

### FEATURES

- Isolation test voltage 5300 V<sub>RMS</sub>
- Interfaces with common logic families
- Input-output coupling capacitance < 0.5 pF
- Industry standard dual-in-line 6 pin package
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC


**RoHS  
COMPLIANT**

### APPLICATIONS

- AC mains detection
- Reed relay driving
- Switch mode power supply feedback
- Telephone ring detection
- Logic ground isolation
- Logic coupling with high frequency noise rejection

### AGENCY APPROVALS

- Underwriters laboratory file #E52744
- DIN EN 60747-5-5 available with option 1

### ORDER INFORMATION

PART	REMARKS
4N35	CTR > 100 %, DIP-6
4N36	CTR > 100 %, DIP-6
4N37	CTR > 100 %, DIP-6
4N38	CTR > 20 %, DIP-6
4N35-X006	CTR > 100 %, DIP-6 400 mil (option 6)
4N35-X007	CTR > 100 %, SMD-6 (option 7)
4N35-X009	CTR > 100 %, SMD-6 (option 9)
4N36-X007	CTR > 100 %, SMD-6 (option 7)
4N36-X009	CTR > 100 %, SMD-6 (option 9)
4N37-X006	CTR > 100 %, DIP-6 400 mil (option 6)
4N38-X009	CTR > 100 %, SMD-6 (option 9)

### Note

For additional information on the available options refer to option information.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
<b>INPUT</b>				
Reverse voltage		$V_R$	6	V
Forward current		$I_F$	60	mA
Surge current	$t \leq 10 \mu\text{s}$	$I_{FSM}$	2.5	A
Power dissipation		$P_{diss}$	100	mW
<b>OUTPUT</b>				
Collector emitter breakdown voltage		$V_{CEO}$	70	V
Emitter base breakdown voltage		$V_{EBO}$	7	V
Collector current		$I_C$	50	mA
	$t \leq 1 \text{ ms}$	$I_C$	100	mA
Power dissipation		$P_{diss}$	150	mW
<b>COUPLER</b>				
Isolation test voltage		$V_{ISO}$	5300	$V_{RMS}$
Creepage			$\geq 7$	mm
Clearance			$\geq 7$	mm
Isolation thickness between emitter and detector			$\geq 0.4$	mm
Comparative tracking index	DIN IEC 112/VDE 0303, part 1		175	
Isolation resistance	$V_{IO} = 500 \text{ V}, T_{amb} = 25 \text{ }^\circ\text{C}$	$R_{IO}$	$10^{12}$	$\Omega$
	$V_{IO} = 500 \text{ V}, T_{amb} = 100 \text{ }^\circ\text{C}$	$R_{IO}$	$10^{11}$	$\Omega$
Storage temperature		$T_{stg}$	- 55 to + 150	$^\circ\text{C}$
Operating temperature		$T_{amb}$	- 55 to + 100	$^\circ\text{C}$
Junction temperature		$T_j$	100	$^\circ\text{C}$
Soldering temperature	max. 10 s dip soldering: distance to seating plane $\geq 1.5 \text{ mm}$	$T_{sld}$	260	$^\circ\text{C}$

**Note**

$T_{amb} = 25 \text{ }^\circ\text{C}$ , unless otherwise specified.

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

ELECTRICAL CHARACTERISTICS <sup>(1)</sup>							
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
<b>INPUT</b>							
Junction capacitance	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		$C_j$		50		pF
Forward voltage <sup>(2)</sup>	$I_F = 10 \text{ mA}$		$V_F$		1.3	1.5	V
	$I_F = 10 \text{ mA}, T_{amb} = - 55 \text{ }^\circ\text{C}$		$V_F$	0.9	1.3	1.7	V
Reverse current <sup>(2)</sup>	$V_R = 6 \text{ V}$		$I_R$		0.1	10	$\mu\text{A}$
Capacitance	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		$C_O$		25		pF
<b>OUTPUT</b>							
Collector emitter breakdown voltage <sup>(2)</sup>	$I_C = 1 \text{ mA}$	4N35	$BV_{CEO}$	30			V
		4N36	$BV_{CEO}$	30			V
		4N37	$BV_{CEO}$	30			V
		4N38	$BV_{CEO}$	80			V
Emitter collector breakdown voltage <sup>(2)</sup>	$I_E = 100 \mu\text{A}$		$BV_{ECO}$	7			V



ELECTRICAL CHARACTERISTICS <sup>(1)</sup>								
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT	
<b>OUTPUT</b>								
Collector base breakdown voltage <sup>(2)</sup>	$I_C = 100 \mu\text{A}, I_B = 1 \mu\text{A}$	4N35	$BV_{CBO}$	70			V	
		4N36	$BV_{CBO}$	70			V	
		4N37	$BV_{CBO}$	70			V	
		4N38	$BV_{CBO}$	80			V	
Collector emitter leakage current <sup>(2)</sup>	$V_{CE} = 10 \text{ V}, I_F = 0$	4N35	$I_{CEO}$		5	50	nA	
		4N36	$I_{CEO}$		5	50	nA	
	$V_{CE} = 10 \text{ V}, I_F = 0$	4N37	$I_{CEO}$		5	50	nA	
	$V_{CE} = 60 \text{ V}, I_F = 0$	4N38	$I_{CEO}$			50	nA	
	$V_{CE} = 30 \text{ V}, I_F = 0,$ $T_{amb} = 100 \text{ }^\circ\text{C}$	4N35	$I_{CEO}$				500	$\mu\text{A}$
		4N36	$I_{CEO}$				500	$\mu\text{A}$
		4N37	$I_{CEO}$				500	$\mu\text{A}$
$V_{CE} = 60 \text{ V}, I_F = 0,$ $T_{amb} = 100 \text{ }^\circ\text{C}$	4N38	$I_{CEO}$		6		$\mu\text{A}$		
Collector emitter capacitance	$V_{CE} = 0$		$C_{CE}$		6		pF	
<b>COUPLER</b>								
Resistance, input output <sup>(2)</sup>	$V_{IO} = 500 \text{ V}$		$R_{IO}$	$10^{11}$			$\Omega$	
Capacitance, input output	$f = 1 \text{ MHz}$		$C_{IO}$		0.5		pF	

**Notes**(1)  $T_{amb} = 25 \text{ }^\circ\text{C}$ , unless otherwise specified.

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

(2) Indicates JEDEC registered value.

CURRENT TRANSFER RATIO							
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN	TYP.	MAX	UNIT
DC current transfer ratio <sup>(1)</sup>	$V_{CE} = 10 \text{ V}, I_F = 10 \text{ mA}$	4N35	$CTR_{DC}$	100			%
		4N36	$CTR_{DC}$	100			%
		4N37	$CTR_{DC}$	100			%
	$V_{CE} = 10 \text{ V}, I_F = 20 \text{ mA}$	4N38	$CTR_{DC}$	20			%
	$V_{CE} = 10 \text{ V}, I_F = 10 \text{ mA},$ $T_A = -55 \text{ to } +100 \text{ }^\circ\text{C}$	4N35	$CTR_{DC}$	40	50		%
		4N36	$CTR_{DC}$	40	50		%
		4N37	$CTR_{DC}$	40	50		%
4N38		$CTR_{DC}$		30		%	

**Note**

(1) Indicates JEDEC registered values.

SWITCHING CHARACTERISTICS							
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT	
Switching time <sup>(1)</sup>	$V_{CC} = 10 \text{ V}, I_C = 2 \text{ mA}, R_L = 100 \Omega$	$t_{on}, t_{off}$		10		$\mu\text{s}$	

**Note**

(1) Indicates JEDEC registered values.

**TYPICAL CHARACTERISTICS**

$T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

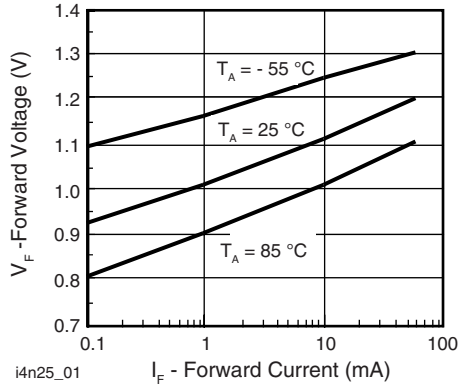


Fig. 1 - Forward Voltage vs. Forward Current

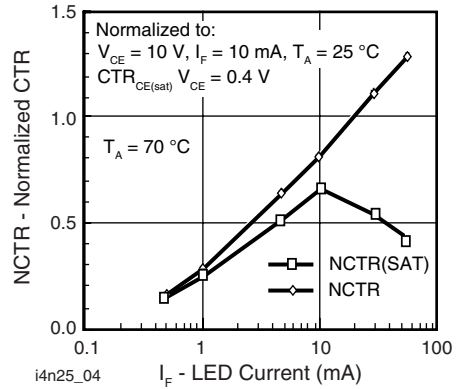


Fig. 4 - Normalized Non-Saturated and Saturated CTR vs. LED Current

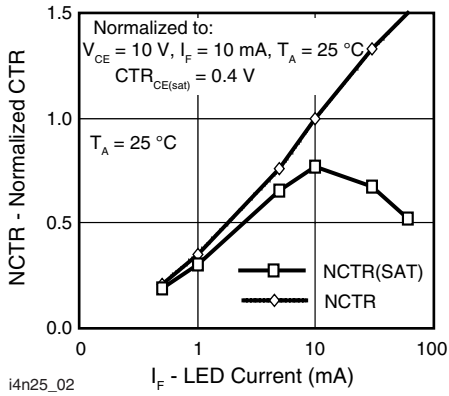


Fig. 2 - Normalized Non-Saturated and Saturated CTR vs. LED Current

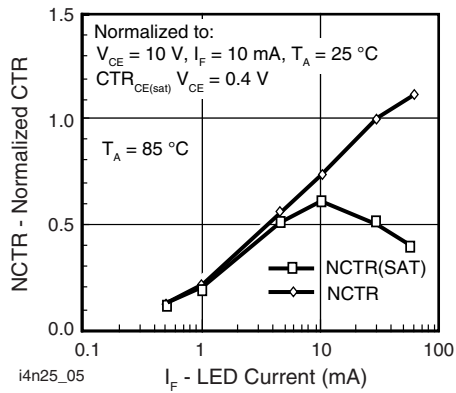


Fig. 5 - Normalized Non-Saturated and Saturated CTR vs. LED Current

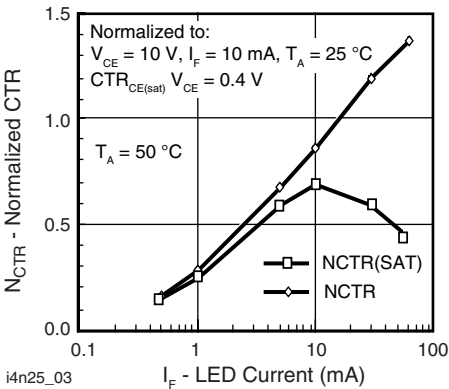


Fig. 3 - Normalized Non-Saturated and Saturated CTR vs. LED Current

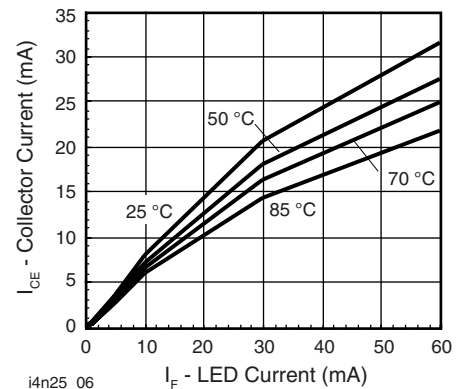


Fig. 6 - Collector Emitter Current vs. Temperature and LED Current

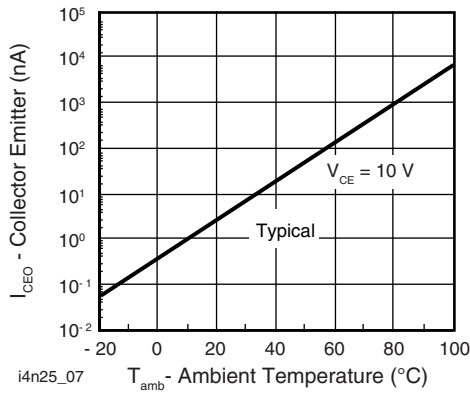


Fig. 7 - Collector Emitter Leakage Current vs. Temperature

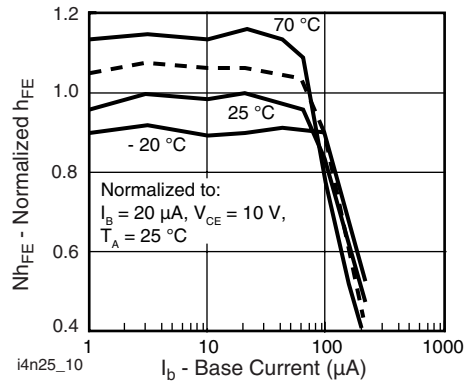
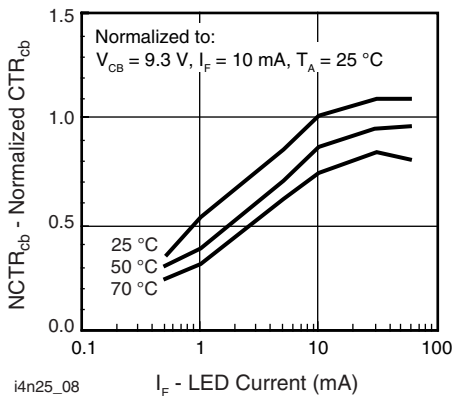

 Fig. 10 - Normalized Non-Saturated  $h_{FE}$  vs. Base Current and Temperature


Fig. 8 - Normalized CTRcb vs. LED Current and Temperature

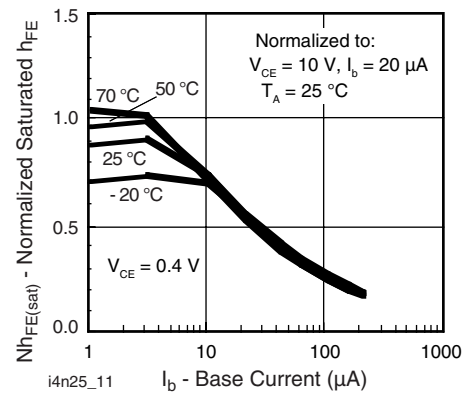
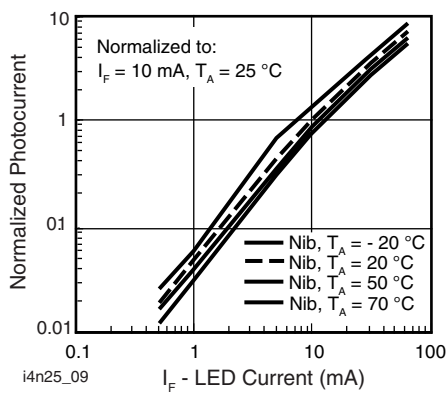
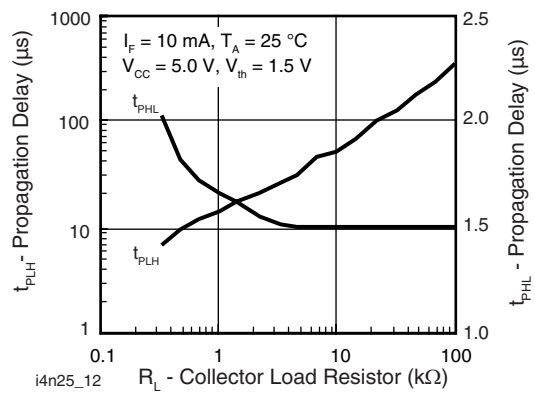
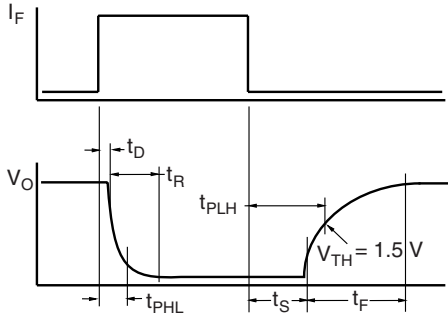

 Fig. 11 - Normalized  $h_{FE}$  vs. Base Current and Temperature

 Fig. 9 - Normalized Photocurrent vs.  $I_F$  and Temperature


Fig. 12 - Propagation Delay vs. Collector Load Resistor

# 4N35/4N36/4N37/4N38

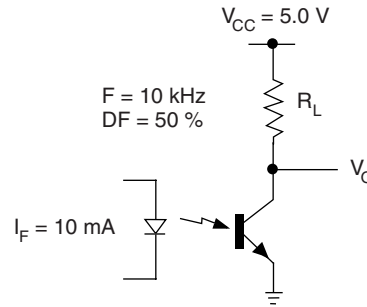


Vishay Semiconductors Optocoupler, Phototransistor Output,  
with Base Connection



i4n25\_13

Fig. 13 - Switching Timing



i4n25\_14

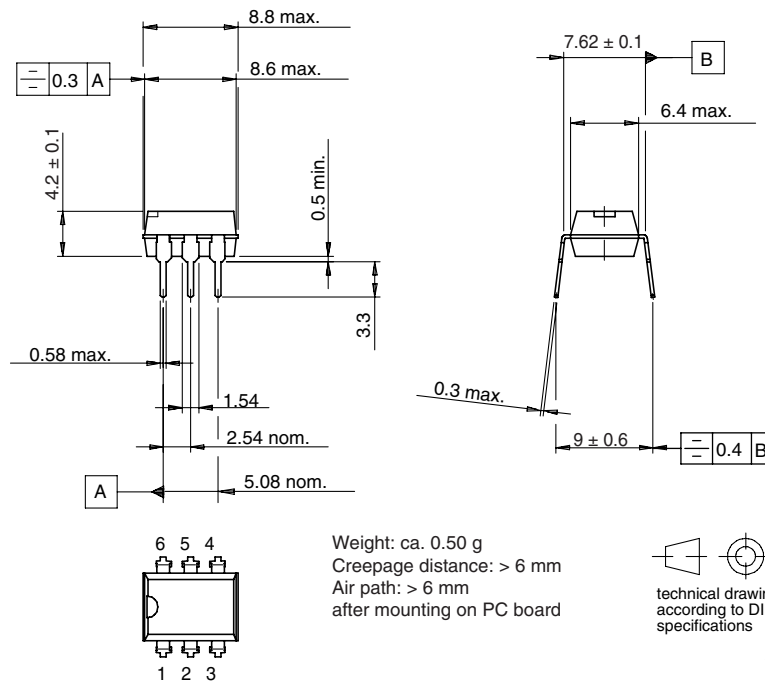
Fig. 14 - Switching Schematic

## PACKAGE DIMENSIONS in millimeters (inches)

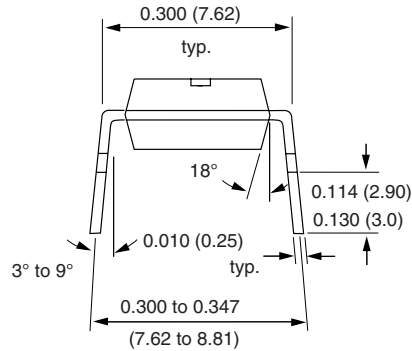
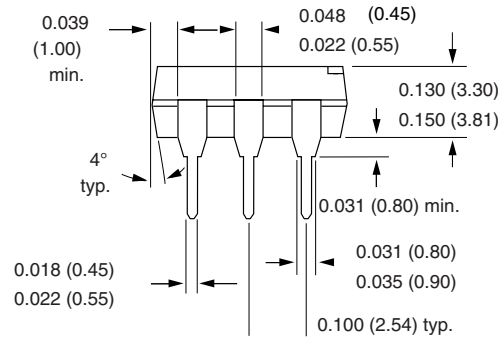
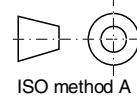
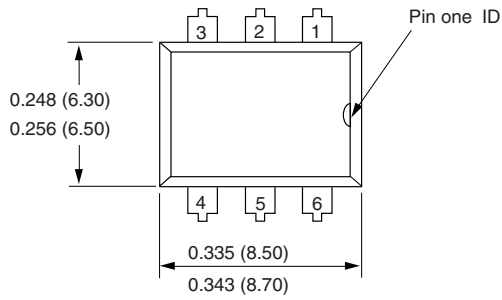
For 4N35/36/37/38..... see DIL300-6 Package dimension in the Package Section.

For products with an option designator (e.g. 4N35-X006 or 4N36-X007)..... see DIP-6 Package dimensions in the Package Section.

### DIL300-6 Package Dimensions

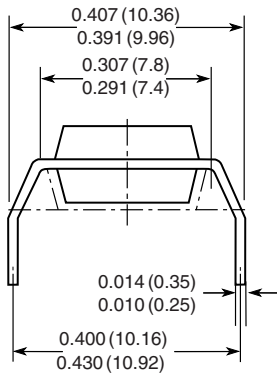


### DIP-6 Package Dimensions

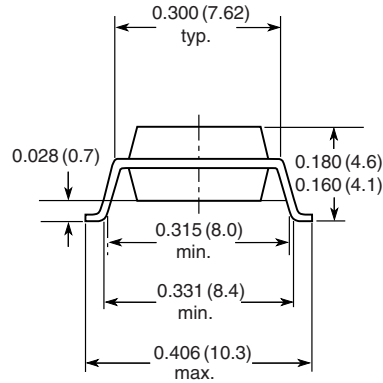


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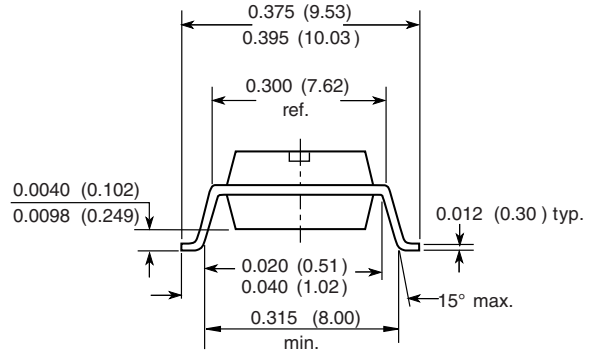
**Option 6**



**Option 7**



**Option 9**



18450



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It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

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Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany





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